What is claimed is:

1. A dual chips stacked packaging structure, comprising:

a first chip, having an active surface and an opposing non-active surface, the active surface consisting of a central area and a peripheral area having a plurality of first bonding pads;

a lead frame, comprising a plurality of leads and a chip paddle having a first adhering surface and a second adhering surface, the first adhering surface adhered to the active surface of the first chip in such a way as to avoid contact with the first bonding pads;

a second chip, having an active surface and an opposing non-active surface connecting with the second adhering surface of the chip paddle, the active surface consisting of a central area and a peripheral area having a plurality of second bonding pads; and

a plurality of wires, wherein parts of the wires electrically connect with the first bonding pad and the leads, and parts of the wires electrically connect with the second bonding pad and the leads.

2. The structure as claimed in claim 1, wherein the first adhering surface of the chip paddle and the active surface of the first chip are adhered by a non-conductive solid or liquid adhesive.

3. The structure as claimed in claim 1, wherein the second adhering surface of the chip paddle and the non-active surface of the second chip are connected by a solid or liquid adhesive.

4. The structure as claimed in claim 1, wherein the wires are metal lines.

5. A dual chips stacked packaging structure, comprising:

a first chip, having an active surface and an opposing non-active surface, wherein the active surface consists of a central area and a peripheral area having a plurality of first bonding pads;

a lead frame comprising a plurality of leads and a chip paddle having a first adhering surface and a second adhering surface, the first adhering surface adhered to the active surface of the first chip in such a way as to avoid contact with the first bonding pads;

a second chip, having an active surface and an opposing non-active surface connecting with the second adhering surface of the chip paddle, wherein the active surface consists of a central area and a peripheral area having a plurality of second bonding pads;

a plurality of wires, parts of which electrically connect with the first bonding pad and the

leads, and parts of which electrically connect with the second bonding pad and the leads; and

an encapsulation, covering the lead frame, the first chip, the second chip, and the wires.

6. The structure as claimed in claim 5, wherein each lead further comprises an inner lead covered by the encapsulation and outer lead extending beyond the encapsulation.

7. The structure as claimed in claim 5, wherein the first adhering surface of the chip paddle and the active surface of the first chip are adhered by a non-conductive solid or liquid adhesive.

8. The structure as claimed in claim 5, wherein the second adhering surface of the chip paddle and the non-active surface of the second chip are connected by a solid or liquid adhesive.

9. The structure as claimed in claim 5, wherein the wires are metal lines.

10. A dual chips stacked packaging structure, comprising:

a first chip, having an active surface and an opposing non-active surface, wherein the active surface consists of a central area and a peripheral area having a plurality of first bonding pads;

a lead frame, comprising a plurality of leads and a chip paddle having a first adhering surface and

a second adhering surface, the first adhering surface adhered to the active surface of the first chip in such a way as to avoid contact with the first bonding pads, and each of the leads comprising a wire connecting surface and a wire non-connecting surface;

a second chip, having an active surface and an opposing non-active surface connecting with the second adhering surface of the chip paddle, wherein the active surface consists of a central area and a peripheral area having a plurality of second bonding pads;

a plurality of wires, parts of which electrically connect with the first bonding pad and the leads, and parts which of electrically connect with the second bonding pad and the leads; and

an encapsulation, covering the chip paddle, the second chip, the wire connecting surface of the leads, the active surface of the first chip, and the wires, with the non-active surface of the first chip and the wire non-connecting surface of the leads exposed beyond the encapsulation.

11. The structure as claimed in claim 10, wherein each lead further comprises an inner lead covered by the encapsulation and outer lead extending beyond the encapsulation.

12. The structure as claimed in claim 10, wherein the first adhering surface of the chip paddle and the

active surface of the first chip are adhered by a non-conductive solid or liquid adhesive.

13. The structure as claimed in claim 10, wherein the second adhering surface of the chip paddle and the non-active surface of the second chip are connected by a solid or liquid adhesive.

14. The structure as claimed in claim 10, wherein the wires are metal lines.